(FILE 'HOME' ENTERED AT 16:25:34 ON 28 DEC 2000)

	FILE			USPATFULL' ENTERED AT 16:25:46 ON 28 DEC 2000
L1		319	S	(FORM# OR FORMING) (1W) (SULFONIC ACID)
L2		63903	s	PHOTORESIST
L3				L1 AND L2
L4		77	S	(DECOMPOSE# OR DECOMPOSING) (5A) (SULFONIC ACID)
L5			-	L2 AND L4
L6				(SULFONIC ACID)/AB
L7		19937	S	PHOTORESIST/AB
F8		253	S	L6 AND L7

() Willand about

441 1-3 Goverll

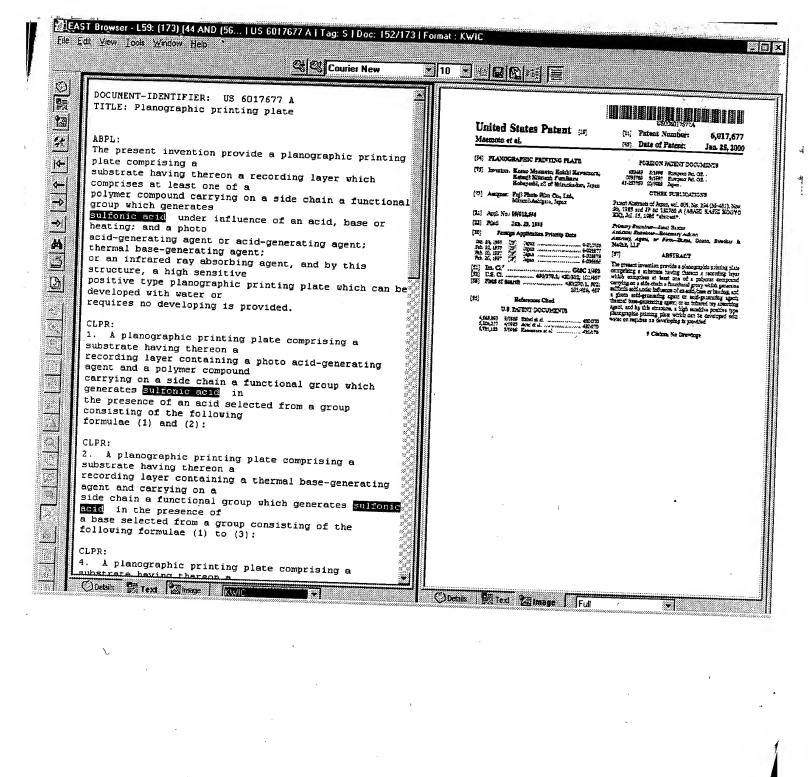
9 - But Aut + ethlackul.

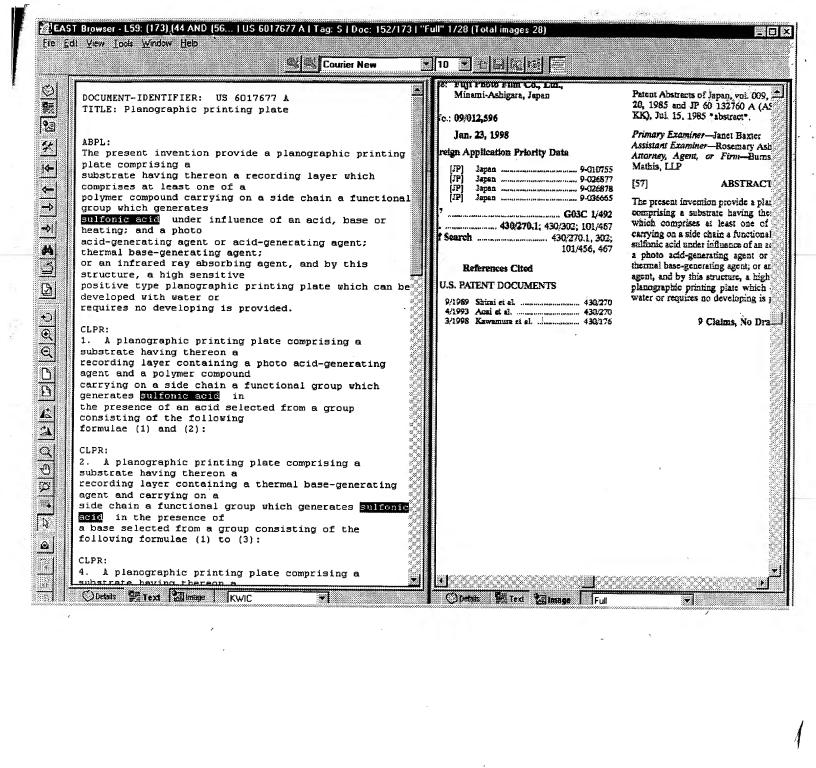
10,11

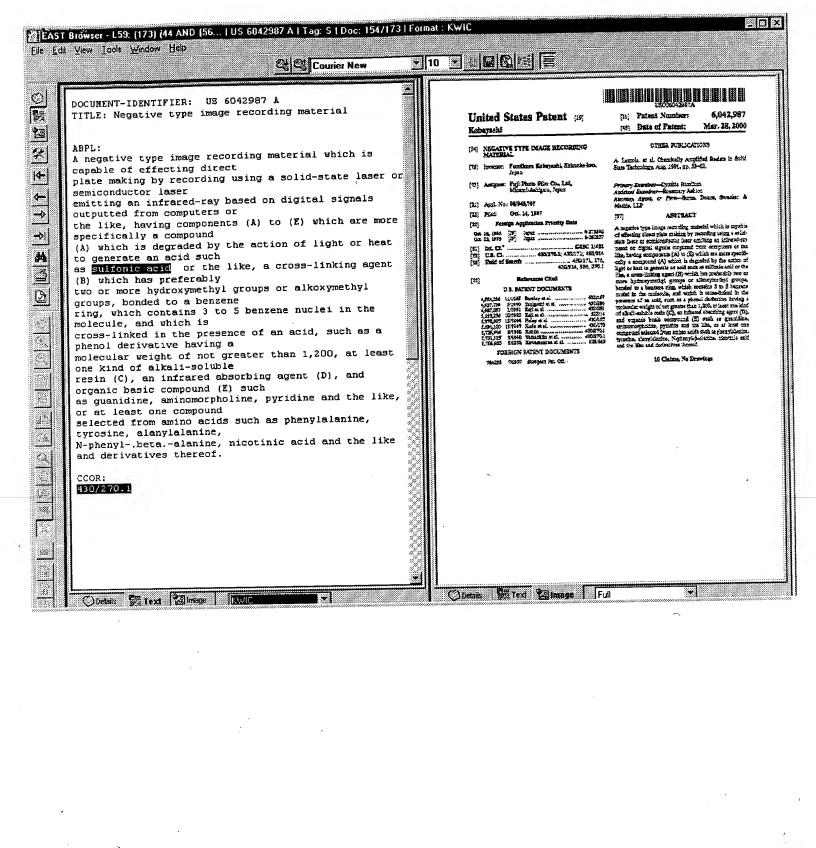
R13-R16 = Acced class + Buhl Sins

12-Base couple.

Obj 184







	www. will be the state of the s						
	Freeform Search						
Database:	US Patents Full-Text Database JPO Abstracts Database EPO Abstracts Database Derwent World Patents Index IBM Technical Disclosure Bulletins						
Term:							
Display:	50 Documents in Display Format: REV Starting with Number 1						
Generate: O Hit List O Hit Count O Image							
***************************************	Search Clear Help Logout Interrupt						
	Main Menu Show S Numbers Edit S Numbers Preferences						

Search History

Today's Date: 12/29/2000

DB Name	Query	Hit Count Set Name		
USPT	13 and 14	92	<u>L6</u>	
USPT	13 and 14	92	<u>L5</u>	
USPT	photoresist or resist.ab.	48881	<u>L4</u>	
USPT	11 and 12	119	<u>L3</u>	
USPT	generat\$3 adj5 (sulfonic adj1 acid)	200	<u>L2</u>	
USPT	compound adj10 generat\$3	14896	<u>L1</u>	

WEST

End of Result Set

Generate Collection

L2: Entry 2 of 2

File: DWPI

Sep 25, 1998

DERWENT-ACC-NO: 1998-572567

DERWENT-WEEK: 200039

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TITLE: Radiation sensitive resin composition processed using e.g. electron beam - comprising resin becoming acid soluble on cleaving acid gp., agent generating acid on irradiation and solvent

PRIORITY-DATA:

1997JP-0074717

March 12, 1997

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

MAIN-IPC

JP 10254139 A

September 25, 1998

N/A

PAGES

G03F007/039

INT-CL (IPC): G03F 7/004; G03F 7/039; H01L 21/027

ABSTRACTED-PUB-NO: JP 10254139A

BASIC-ABSTRACT:

A radiation sensitive resin composition includes (A) a resin composed of alkali insoluble or alkali slightly soluble acid cleavage gp-containing resin having an alicyclic structure in a main chain and/or a side chain, and becoming alkali soluble when the acid cleavage gp is cleaved, (B) a radiation sensitive acid generating agent generating acid by irradiation and (C) a solvent compose of a mixture of a straight chained ketone, and at least one kind of circular ketone, propylene glycol monoalkylether acetate, and alkyl 2-hydroxypropionic acid.

USE - Effectively used in the fine processing using far UV such as ArF excimer laser, X-ray such as synchrotron radiation, a charged particle beam such as electron beam, or the like.

 ${\tt ADVANTAGE\ -\ High\ transparency\ to\ radiation,\ dry\ etching\ resistance,\ uniform\ film\ thickness}$

Generate Collection

L2: Entry 1 of 2

File: JPAB

Sep 25, 1998

PUB-NO: JP410254139A

DOCUMENT-IDENTIFIER: JP 10254139 A

TITLE: RADIATION SENSITIVE RESIN COMPOSITION

PUBN-DATE: September 25, 1998

INVENTOR-INFORMATION:

NAME

SUWA, MITSUFUMI IWAZAWA, HARUO KAJITA, TORU

IWANAGA, SHINICHIRO

INT-CL (IPC): G03F 7/039; G03F 7/004; G03F 7/004; H01L 21/027

ABSTRACT:

PROBLEM TO BE SOLVED: To obtain a resist pattern excellent in radiation transmitting property and dry etching resistance by incorporating a specified resin, a radiation sensitive acid producing agent and a solvent mixture of straight chain ketone with cyclic ketone, etc.

SOLUTION: This radiation sensitive resin compsn. contains an alkali-insoluble or slightly alkali-soluble resin having an alicyclic skeleton in the principal chain and/or a side chain, contg. acid-cleavable groups and convertible into an alkali-soluble resin when the groups are cleaved, a radiation sensitive acid generating agent that produces an acid when irradiated and a solvent mixture of straight chain ketone with at least one selected from among cyclic ketone, propylene glycol monoalkyl ether acetate and alkyl 2-hydroxypropionate. A resist pattern excellent in uniformity in film thickness, adhesiveness to the substrate, sensitivity, resolution, etc., can be formed.

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